



CORNING

**Corning Laser Technologies GmbH**

**Introduction of Corning Laser Technologies'  
Wafer Process Solutions**

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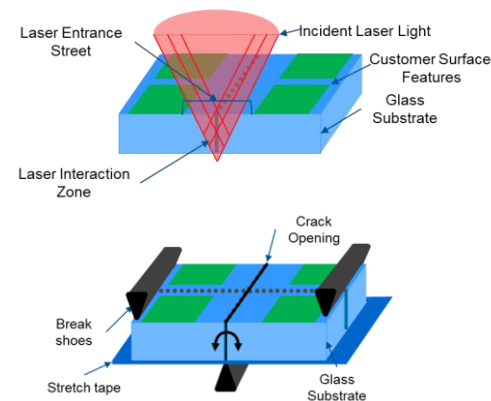
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# Corning Laser Technologies provides glass processing solutions with combined strength of our expertise in materials and processes

- Corning Laser Technologies combines over 25 years of experience in designing laser-based machine tools with Corning Incorporated's deep understanding of material science. We provide:
  - Innovative laser glass cutting and drilling technologies with distinct advantages over conventional processes
  - Laser glass processing systems capable of processing 2D and 3D-shaped glass, such as Corning® Gorilla® Glass, Lotus™ NXT, and Eagle XG® glass, plus other chemically strengthened and non-strengthened glass types including soda-lime and other brittle materials.
- Our unique wafer process solution pairs Corning® laser dicing and Dynatex mechanical breaking technology. Designed for semiconductor-related industry, this process provides a fast, precise, clean, and debris free process with high process speed, enabling Zero-kerf cutting which increases material utilization and die density



CLT 500X Platform



**For more information on  
Corning Laser Technologies GmbH  
please visit our website.**



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